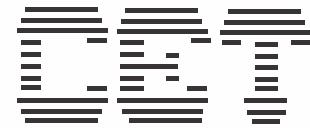


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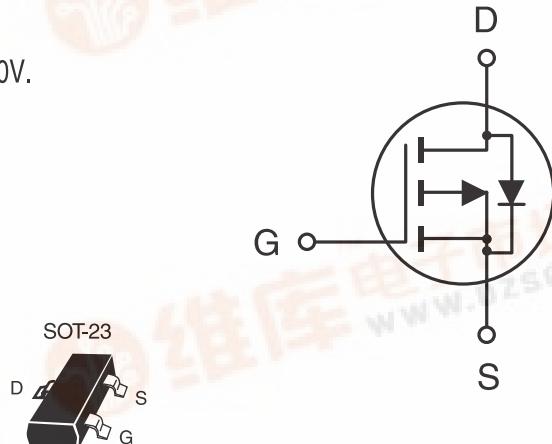
PRELIMINARY

## P-Channel Enhancement Mode MOSFET

### FEATURES

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- -50V, -0.13A,  $R_{DS(ON)}=10\Omega$  @  $V_{GS}=-10V$ .
- High dense cell design for low  $R_{DS(ON)}$ .
- Rugged and reliable.
- Surface Mount Package.



### ABSOLUTE MAXIMUM RATINGS ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-50	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous <sup>a</sup> @ $T_J=125^\circ C$ -Pulsed <sup>b</sup>	$I_D$	-0.13	A
	$I_{DM}$	-0.52	A
Drain-Source Diode Forward Current <sup>a</sup>	$I_S$	-0.13	A
Maximum Power Dissipation <sup>a</sup>	$P_D$	0.36	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ C$

### THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Ambient <sup>a</sup>	$R_{\theta JA}$	350	$^\circ C/W$
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## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-50			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -50V, V_{GS} = 0V$			-15	$\mu A$
Gate-Body Leakage	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 10$	nA
<b>ON CHARACTERISTICS<sup>b</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -1mA$	-0.8	-1.75	-2	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS} = -10V, I_D = -0.13A$		2.3	10	$\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS} = -10V, I_D = -0.13A$	0.05	0.27		S
<b>DYNAMIC CHARACTERISTICS<sup>c</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = -25V, V_{GS} = 0V$ $f = 1.0MHz$		37	45	pF
Output Capacitance	$C_{oss}$			16	25	pF
Reverse Transfer Capacitance	$C_{rss}$			5	12	pF
<b>SWITCHING CHARACTERISTICS<sup>c</sup></b>						
Turn-On Delay Time	$t_{D(ON)}$	$V_{DD} = -30V,$ $I_D = -0.27A,$ $V_{GS} = -10V,$ $R_{GEN} = 50\Omega$		9	12	ns
Rise Time	$t_r$			38	50	ns
Turn-Off Delay Time	$t_{D(OFF)}$			8	10	ns
Fall Time	$t_f$			19	25	ns

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## ELECTRICAL CHARACTERISTICS ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ <sup>c</sup>	Max	Unit
<b>DRAIN-SOURCE DIODE CHARACTERISTICS<sup>b</sup></b>						
Diode Forward Voltage	$V_{SD}$	$V_{GS} = 0V, I_S = -0.26A$		-0.95	-1.2	V

### Notes

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- a. Surface Mounted on FR4 Board,  $t \leq 10\text{sec}$ .
- b. Pulse Test: Pulse Width  $\leq 300\ \mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
- c. Guaranteed by design, not subject to production testing.

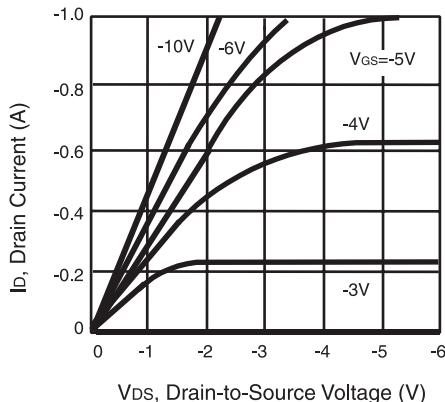


Figure 1. Output Characteristics

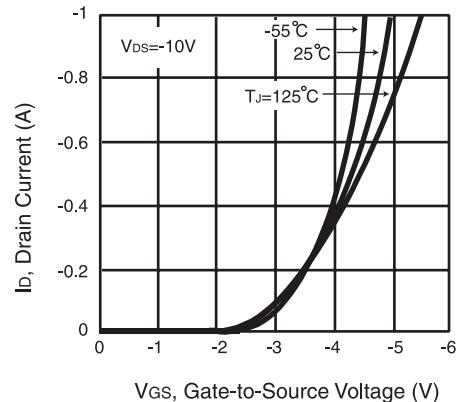


Figure 2. Transfer Characteristics

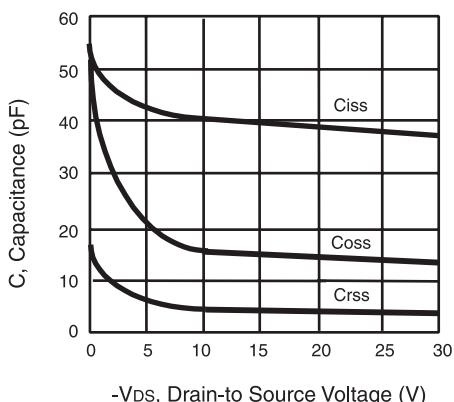


Figure 3. Capacitance

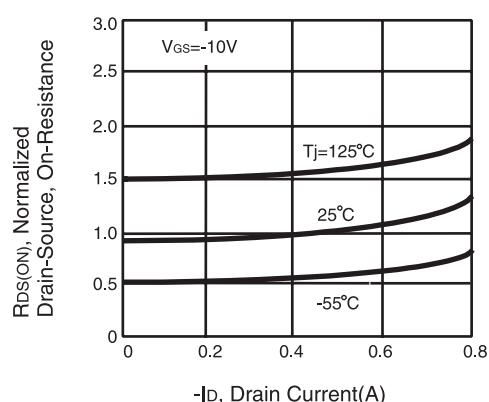
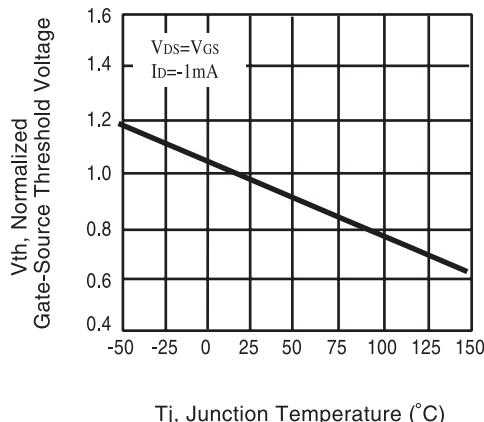
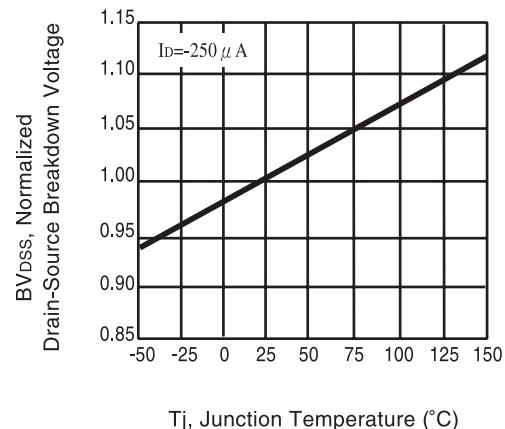


Figure 4. On-Resistance Variation with Drain Current and Temperature

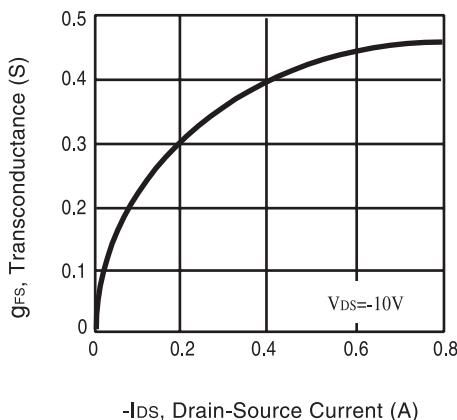
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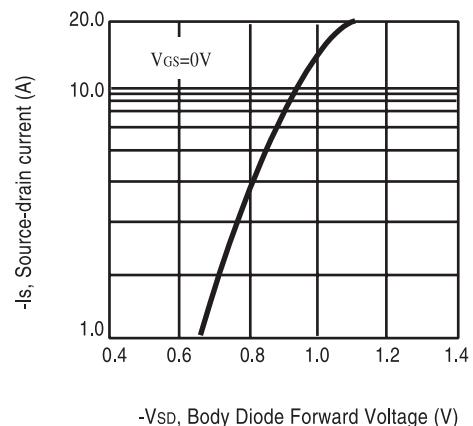
**Figure 5. Gate Threshold Variation with Temperature**



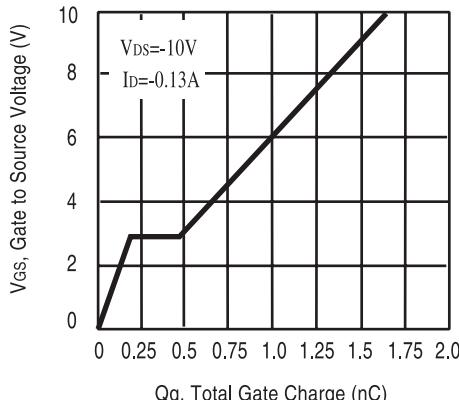
**Figure 6. Breakdown Voltage Variation with Temperature**



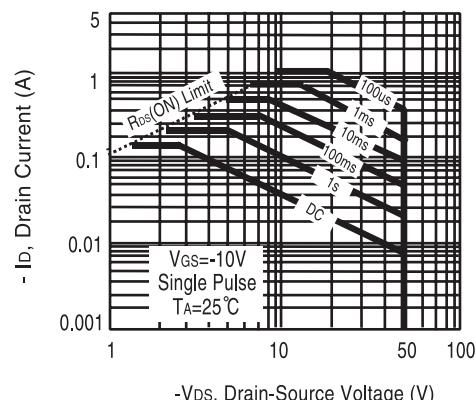
**Figure 7. Transconductance Variation with Drain Current**



**Figure 8. Body Diode Forward Voltage Variation with Source Current**



**Figure 9. Gate Charge**



**Figure 10. Maximum Safe Operating Area**

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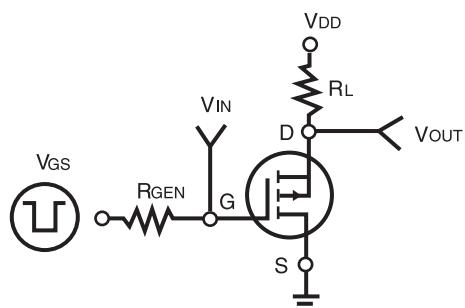


Figure 11. Switching Test Circuit

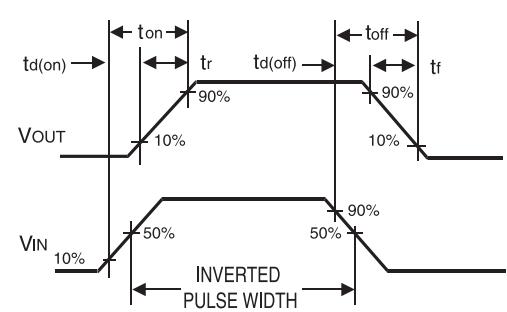


Figure 12. Switching Waveforms

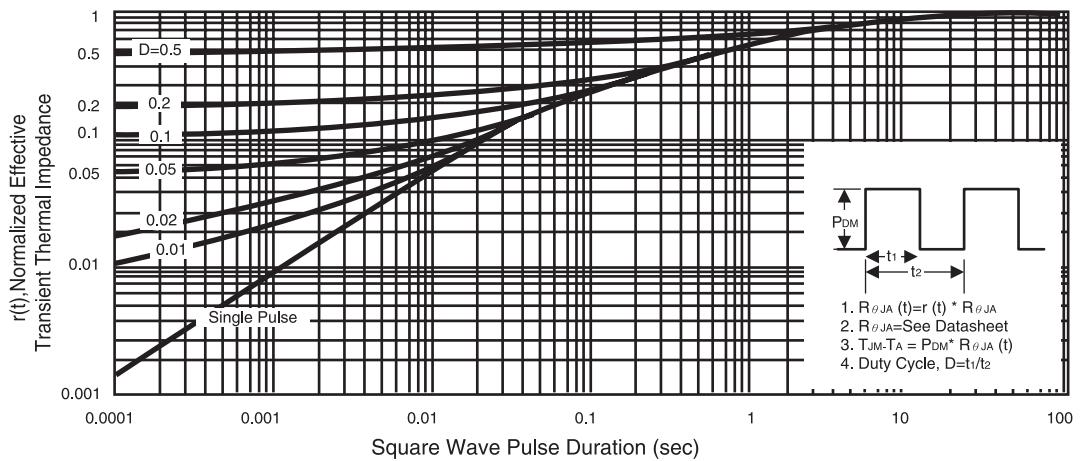


Figure 13. Normalized Thermal Transient Impedance Curve